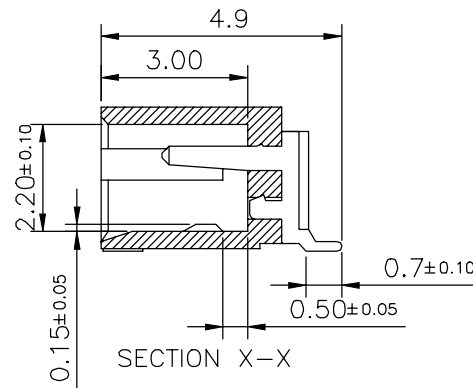
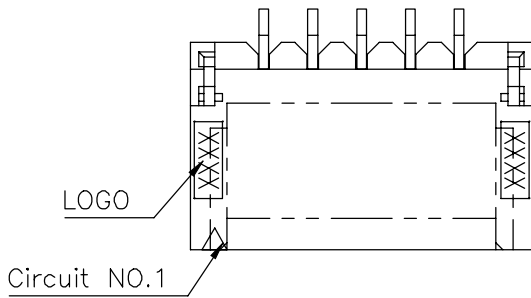


NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1:GOLD FLASH PLATING ON CONTACT AND SOLDER.
 - C:15u" GOLD ON CONTACT
 - 2.2 FITTING NAIL:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1:GOLD FLASH PLATING ON CONTACT AND SOLDER.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50224-XXXX-XXX
5. PACKAGE PLS. REFER TO 87213-XXXX-TRP
6. PART NUMBER



51325-XXXX-XXX

NO. OF CKT ————

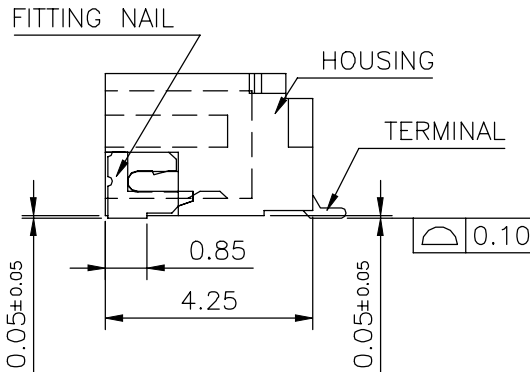
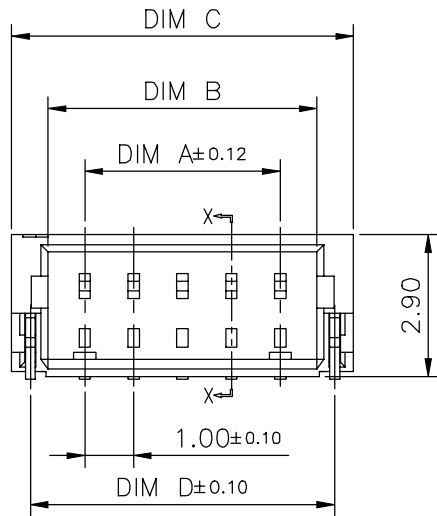
PACKING ————

PLATING ————

XXX	HALOGEN FREE	COLOR
001	HF	BLACK

0:TAPE & REEL
1:TUBE PACKAGE

1:GOLD FLASH
C:15u" GOLD ON CONTACT



CKT	DIM A	DIM B	DIM C	DIM D
004	3.0	4.4	6.0	5.23

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Huang, Shun Sen DATE 21/10/08			
	CHECKED BY Lu, Jing Quan DATE 21/10/08		TITLE 1.0 mm WTB WAFER CONN. SMT S/R R/A TYPE	
	APPROVED BY hsieh, fu yu DATE 21/10/08	UNITS mm	SIZE A4	RFG NO. NA
	SCALE 2:1	SHEET NO. 1 OF 1	REV C	DWG NO. 51325-XXXX-XXX